

Appl. No. 10/674,831
HSJ920030026US1/(2004300-0514-B-DWL)
Amdt. Dated September 6, 2005
Reply to Office Action of May 6, 2005

In the Specification

Please replace the original title with the replacement titled provided below:

**“APPARATUS HAVING A HARD BIAS SEEDLAYER STRUCTURE FOR PROVIDING
IMPROVED PROPERTIES OF A HARD BIAS LAYER”**